

**AMENDMENTS TO THE CLAIMS, COMPLETE LISTING OF CLAIMS IN
ASCENDING ORDER WITH STATUS INDICATOR**

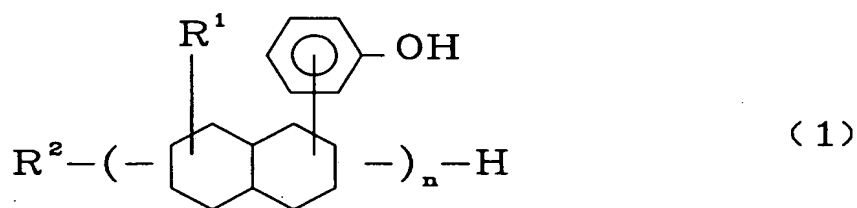
Please amend the following claims as indicated.

1. (Original) A thermosetting resin composition characterized as containing an epoxy resin having an epoxy equivalent weight of 100 – 2,000, an epoxy hardener in the form of a compound having a phenol group, and a layered silicate in the amount of 0.2 - 100 parts by weight, based on 100 parts by weight of resin constituents including said epoxy resin and epoxy hardener.

2. (Original) The thermosetting resin composition as recited in claim 1, characterized in that said epoxy resin contains at least one type selected from the group consisting of a bisphenol epoxy resin, biphenyl epoxy resin, dicyclopentadiene epoxy resin and naphthalene epoxy resin.

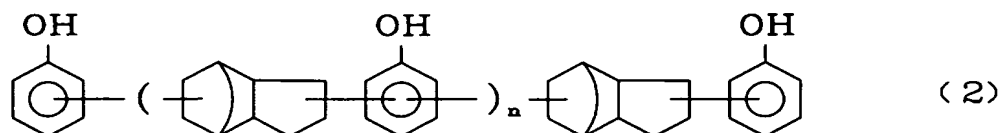
3. (Currently Amended) The thermosetting resin composition as recited in claim 1 or 2, characterized in that said epoxy hardener comprises at least one type selected from the group consisting of hydrophobic phenol compounds represented by the following formulas (1) - (3):

[Chemical 1]



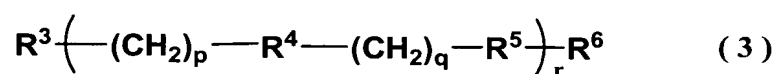
(In the formula (1), R¹ denotes methyl or ethyl, R² denotes hydrogen or a hydrocarbon group and n indicates an integer of 2 – 4)

[Chemical 2]



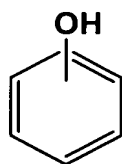
(In the formula (2), n indicates 0 or an integer of 1 – 5) and

[Chemical 3]

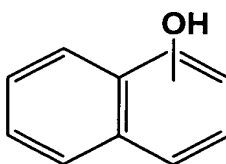


(In the formula (3), R^3 denotes a group represented by the following formula (4a) or (4b), R^4 denotes a group represented by the following formula (5a), (5b) or (5c), R^5 denotes a group represented by the following formula (6a) or (6b), R^6 denotes hydrogen or a molecular chain group containing 1 – 20 carbon atoms, p and q independently indicate an integer of 1 – 6, and r indicates an integer of 1 – 11).

[Chemical 4]

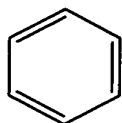


(4a)

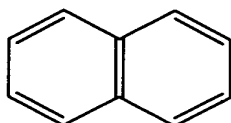


(4b)

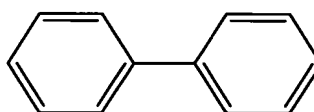
[Chemical 5]



(5a)

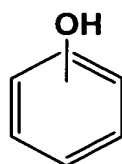


(5b)

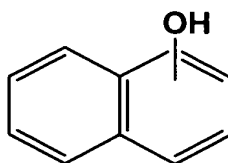


(5c)

[Chemical 6]



(6a)



(6b)

4. (Currently Amended) The thermosetting resin composition as recited in ~~any one of~~ claims claim 1—3, characterized in that said layered silicate comprises at least one type selected from the group consisting of montmorillonite, hectorite, swelling mica and vermiculite.

5. (Currently Amended) The thermosetting resin composition as recited in ~~any one of~~ claims claim 1—4, characterized in that said layered silicate contains at least one type of ammonium salt selected from the group consisting of alkyl ammonium salt containing 6 or more carbon atoms, aromatic quaternary ammonium salt and heterocyclic quaternary ammonium salt.

6. (Original) A resin sheet characterized as comprising the thermosetting resin composition as recited in any one of claims 1 - 5.

7. (Original) A resin sheet characterized in that it is obtained by curing the resin sheet as recited in claim 6.

8. (Currently Amended) The resin sheet as recited in ~~claim 6 or 7~~ claim 6—7, characterized in that a part or all of said layered silicate is dispersed in the form of a stack consisting of 5 or less layers and has a mean interlayer spacing of at least 3 nm along the (001) plane when measured by a wide-angle X-ray diffraction method.

9. (Currently Amended) The resin sheet as recited in ~~any one of claims claim~~ claim 6—8, characterized in that it exhibits a mean linear expansion coefficient (α_1) of not exceeding $4.0 \times 10^{-5} / ^\circ\text{C}$ over a temperature range that is 10 – 50 $^\circ\text{C}$ lower than a glass transition temperature of a cured product of said thermosetting resin composition.

10. (Currently Amended) The resin sheet as recited in ~~any one of claims claim~~ claim 6—9, characterized in that it exhibits a mean linear expansion coefficient (α_2) of not exceeding $4.0 \times$

10^{-5} /°C over a temperature range that is 10 – 50 °C higher than a glass transition temperature of a cured product of said thermosetting resin composition.

11. (Currently Amended) The resin sheet as recited in ~~any one of claims~~ claim 6—10, characterized in that a cured product of said thermosetting resin composition exhibits a dielectric constant at 1 GHz of not exceeding 3.3 and a dielectric loss tangent at 1 GHz of not exceeding 0.015.

12. (Currently Amended) A resin sheet for insulating substrate, characterized as comprising the resin sheet as recited in ~~any one of claims~~ claim 6—11.